

PACKAGE INFORMATION

The chip die is housed in a custom 24-pin CQFN package shown in Fig. 1. The package provides a center heat slug located on its back side to be used for heat dissipation. ADSANTEC recommends for this section to be soldered to the vcc plain, which is ground for a negative supply, or power for a positive supply.

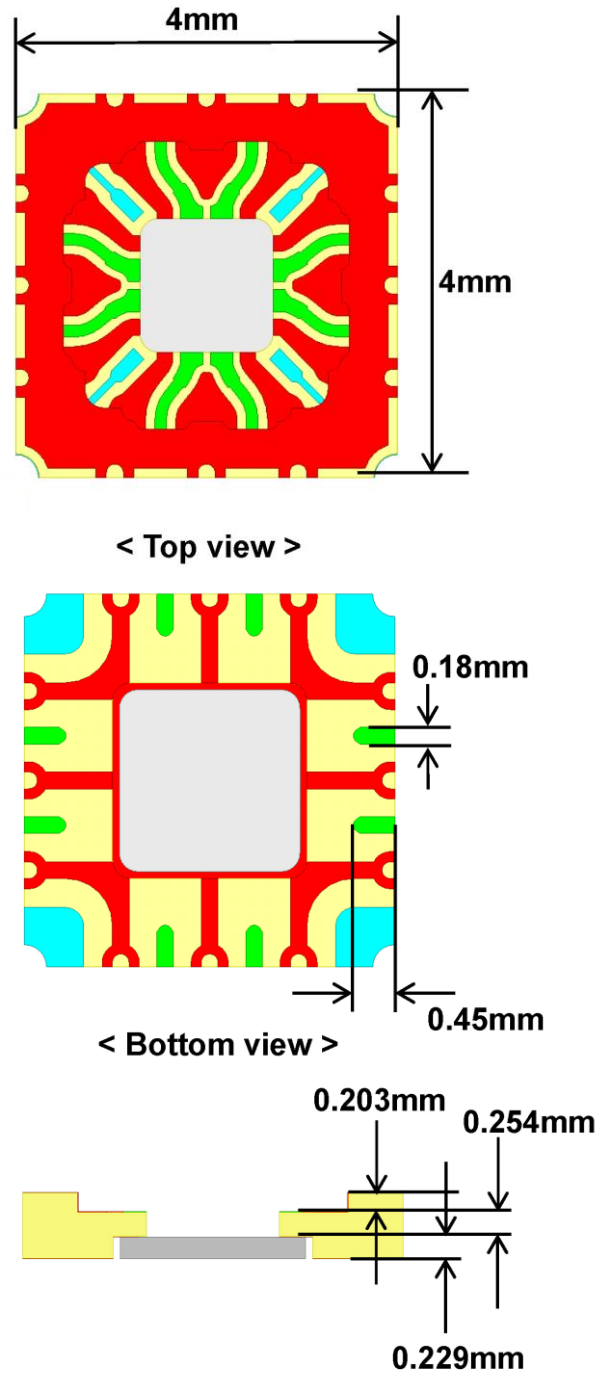


Fig. 1. CQFN 24-Pin Package Drawing (All Dimensions in mm)